IN THE SPECIFICATION

At page 2, lines 14 to 16, amend the specification as follows:

To achieve this object, (1) the inventive method has the features of ~~Claim 1~~ a method for alternately contacting two wafer-like component composite arrangements consisting of a plurality of cohesively designed similar components, in particular of a semiconductor wafer with a function component wafer for manufacturing electronic modules on a wafer level, in which the two component composite arrangements, each provided with contact metallizations on their opposing contact surfaces, are brought into a coverage position with their contact metallizations to form contact pairs, in which position the contact metallizations that are to be joined together are pressed against one another, the contact metallizations being thereby contacted by exposing the rear of one of the component composite arrangements to laser radiation, whereby the wavelength of the laser radiation is selected as a function of the degree of absorption of the component composite arrangement exposed to laser radiation at the rear, so that transmission of the laser radiation through the component composite arrangement exposed to the laser radiation at the rear is essentially suppressed or absorption of the laser radiation takes place essentially in the contact metallizations of one or both component composite arrangements[[,]]; (2) the inventive device has the features of ~~Claim 9~~ a device for alternately contacting two wafer-like component composite arrangements

consisting of a plurality of cohesively designed identical components, in particular of a semiconductor wafer having a function component wafer for manufacturing electronic modules, having a receiving frame for supporting and holding the first component composite arrangement on a transparent panel arranged in the receiving frame, having a diode laser composite arrangement arranged inside the receiving frame and separated from the component composite arrangement by the transparent panel, having a holding clamp for receiving the second component composite arrangement such that contact surfaces of the component composite arrangements provided with contact metallizations are arranged opposite one another, having a positioning device for relative positioning of the component composite arrangements such that the contact metallizations to be joined together form contact pairs, and having a pressure device for generating a contact pressure between the contact metallizations of the contact pairs; and (3) the inventive component composite has the features of ~~Claim 17~~ a component composite comprised of two wafer-like component composite arrangements to be contacted alternately with a first transparent component composite arrangement comprised of a plurality of cohesively designed transparent cover elements and a second component composite arrangement comprised of a plurality of cohesively designed sensor units each having at least one sensor each of which is brought into contact with a substrate unit of a sensor unit which is equipped with through-contacts for rear contact access to the sensor unit.